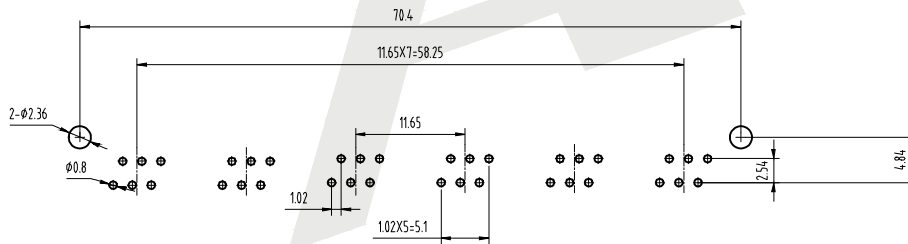
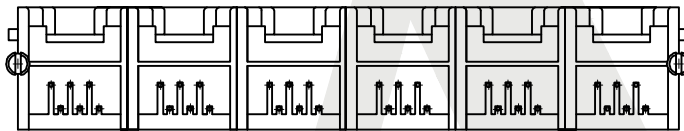
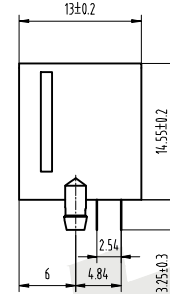
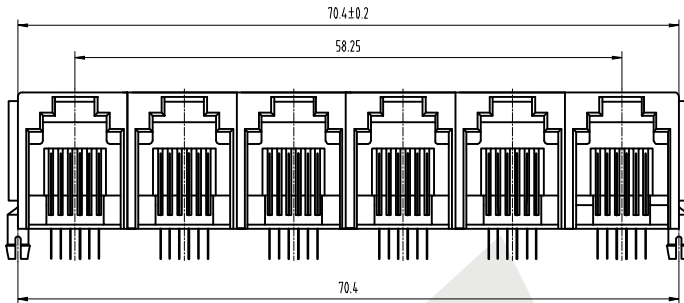


HSF



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

- 1. HOUSING MATERIAL :GLASS FILLED POYESTER UL94V-0.
- 2. CONTACT MATERIAL :PHOSPHOR BRONZE t=0.3mm
- 3. PLATING :SELECTING GOLD PLATING 1μ~50μ" OVER NICKEL IN CONTACT AREA. 150μ" TIN PLATIN. OVER NICKEL IN SOLDER AREA
- 4. SHIELD :0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

- 1. VOLTAGE RATING :125VAC RMS
- 2. CURRENT RATING :1.5AMP
- 3. CONTACT RESISTANCE:30MILLIOHMS MAX
- 4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
- 5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL

- 1. DURRABILITY :750 CYCLES MIN
- 2. PCB RETENTON PRB-SOLDER :1 LB MIN

REVRONMENTAL

- 1. STORAGE :-40° C TO 85° C
- 2. OPERATION :0° C TO 70° C

Order code:

ATRJ5522 — 6P — 6C — X — A — E — A
① — ② — ③ — ④ — ⑤ — ⑥ — ⑦

① SERIES NO:

② NUMBER OF POSITIONS (8P, 6P, 4P)

③ NUMBER OF CONTACTS (8C, 6C, 4C)

④ Contact Plating

G0:Gold flash

G1: 3U" Gold

G2: 5U" Gold

G3: 10U" Gold

G4: 15U" Gold

G5: 30U" Gold

SN: Tin

⑤ Shield

A:W/O Shield

B:Half Shield

C:Shield W/Eml

D:Shield W/O Eml

⑥ Ports

A:1X1P

B:1X2P

C:1X4P

D:1X5P

E:1X6P

F:1X8P

⑦ With Panel or not

A:With panel

B:Without panel

Unless Otherwise specified tolerance
X. ±0.35 X.XX:±0.20
X.X:±0.25 X.XXX:±0.15

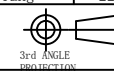
Antenk ANTENK ELECTRONICS CO.,LTD
Http://www.antenk.com
E-mail:sales@antenk.com

SCALE: As Shown UNIT: mm
DRAW Wu Sai DATE 22/03/2018
CHECK BobYang DATE 22/03/2018

TITLE: RJ11 Jack side entry, Full Plastic, 1X6P with panel

DRAWING NO: ATRJ5522-6P6C-X-A-E-A

PRODUCT NO: ATRJ5522-6P6C-X-A-E-A



D

D

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		